

Amendments to the Claims:

A listing of the claims will replace all prior versions and listing of claims in the application:

Listing of Claims:

Claims 1-7 are cancelled without prejudice or disclaimer.

8. (Amended) A method for associating information with a wafer in a semiconductor processing facility, comprising the steps of:

- (1) processing a wafer at a first wafer processing tool, and storing first information pertaining to said wafer on a traveling information file,
wherein said traveling information file comprises information pertaining to the status of said wafer;
- (2) transferring said wafer to a second wafer processing tool;
- (3) transferring said traveling information file with said wafer to said second wafer processing tool;
- (4) receipt of said traveling information file by said second wafer processing tool; and
- (5) processing said wafer at said second processing tool using said first information in said wafer status file to modify said wafer, and storing second information pertaining to said wafer on said traveling information file.

Claims 9-35 are cancelled without prejudice or disclaimer.

36. (Amended) A method for associating information with a wafer in a semiconductor processing facility, comprising the steps of:

(1) processing a wafer at a first wafer processing tool, and storing first information pertaining to said wafer on a wafer information entity,

wherein said wafer information entity comprises information pertaining to the status of said wafer;

(2) transferring said wafer to a second wafer processing tool;

(3) transferring said wafer information entity with said wafer to said second wafer processing tool;

(4) receiving said wafer information entity by said second wafer processing tool;

(5) processing said wafer at said second processing tool using said first information in said wafer information entity to modify said wafer, and storing second information pertaining to said wafer on said wafer information entity.

37. (Amended) A method for associating information with a wafer in a semiconductor processing facility, comprising the steps of:

(1) processing a first wafer at a first wafer processing tool, and storing first information pertaining to said first wafer on a wafer information entity,

wherein said wafer information entity comprises information pertaining to the status of said first wafer;

(2) transferring said first wafer to a second wafer processing tool;

(3) transferring said wafer information entity with said first wafer to said second wafer processing tool;

(4) receiving said wafer information entity by said second wafer processing tool;

(5) processing said first wafer at said second processing tool using said first information in said wafer status file to modify said wafer, and storing second information pertaining to said first wafer on said wafer information entity;

(6) transferring at least some of said second information to said first wafer processing tool;
and

(7) processing a second wafer at said first wafer processing tool using said at least some of said second information of said step (6).

38. (Original) The method of claim 37, wherein wafer information entity contains a recipe or a modification of said recipe, and wherein said first wafer processing tool comprises the step of using said recipe or said modification of said recipe in said wafer information entity to process said wafer.

Claims 39-59 are cancelled without prejudice or disclaimer.